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Jameco Part Number 668511



PRODUCT SPECIFICATION

1.27mm Pitch 184 Ckts 25 Deg. DDR DIMM

1.0 SCOPE

This specification covers the performance requirements of the 1.27 mm centerline angled DDR DIMM socket for board to board interconnect for 1.27 ± 0.10 thick memory modules.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER (S)

Series Number
87623

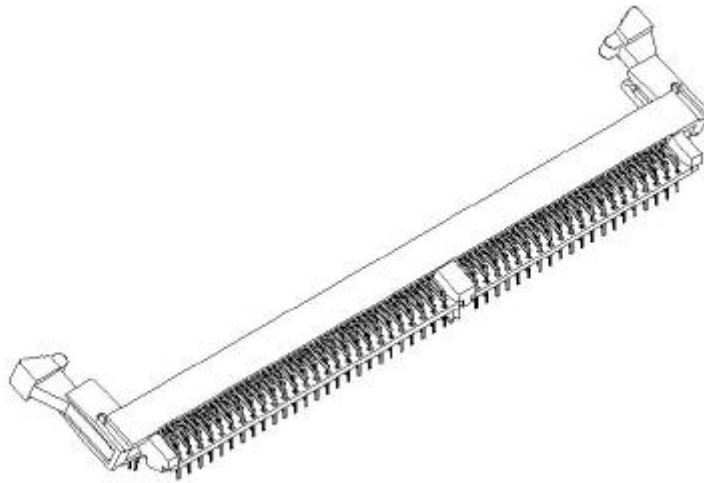
Product Descriptions
1.27mm Pitch 184 Ckts 25 Deg. DDR DIMM

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate Sales Drawings for information on dimensions, materials, plating and markings, recommended module outlines and footprint Specifications.

2.3 SAFETY AGENCY APPROVALS

UL File : E29179
CSA File : 1041513 (LR19980)



REVISION: A	ECR/ECN INFORMATION: EC No: S2006-0558 DATE: 2005/11/16	TITLE: 1.27mm Pitch 184 Ckts 25 Deg. DDR DIMM	SHEET No. 1 of 12
DOCUMENT NUMBER: PS-87623-002	CREATED / REVISED BY: KY TANG 2005/11/21	CHECKED BY: JTAN 2005/11/21	APPROVED BY: GG LEE 2005/11/21



PRODUCT SPECIFICATION

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

The following documents are part of this specification between the requirements of this specified herewith. In the event of conflict between the requirements of this specification and the product drawings, the product drawings shall take precedence. In the event of conflict between the requirements of this specification and reference documents, this specification shall take precedence.

4.0 RATINGS

4.1 VOLTAGE

50 Volts AC (RMS) DC

4.2 CURRENT

1.0 Amps/ pin

4.3 FIELD LIFE AND TEMPERATURE

Field Life: 3 years

Field Temperature: 60°C

4.4 OPERATING TEMPERATURE

-40°C TO +85°C

5.0 PERFORMANCE

5.1 ELECTRICAL PERFORMANCE

Item		Test Condition	Requirement
5-1-1	Contact Resistance	Mate connectors with a maximum voltage of 20 mV and a current of 10 mA (measurement location in section 8.3)	Contact Resistance: 40 mohms max (initial) 10 mohms max change from initial
5-1-2	Insulation Resistance	Mate connectors with a voltage of 500V DC between adjacent terminals or ground	1000 Mohms minimum
5-1-3	Dielectric Withstanding voltage	Mate connectors with a voltage of 500V AC (rms) for 1 minute between adjacent terminals and grounds	No breakdown
5-1-4	Capacitance	Measure between adjacent terminals at 1 MHz (loaded: 50 ohms impedance)	Loaded: 2 picofarads maximum

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5.2 MECHANICAL PERFORMANCE

Item		Test Condition	Requirement
5-2-1	Terminal Retention Force in Housing	Apply an axial pull force on the terminal in the housing at a rate of 25±6 mm per minute	0.40kgf (0.88 lbs) minimum
5-2-2	Durability	Mate connectors up to 25 cycles at a maximum rate of 10 cycles per minute prior to define environmental tests	Contact Resistance: 10 mohms maximum change from initial
5-2-3	Vibration (Mil-std-1344 Method 2005.1 condition I)	Amplitude: 1.5mm peak to peak Sweep: 10-55-10 Hz in one minute Duration: 2 hours in each X-Y-Z axis (Test module shall be per section 8.2)	Contact Resistance: 10 mohms maximum change from initial Discontinuity: Not greater than 1 micro-second
5-2-4	Mechanical shock (Mil-std-1344 Method 2004.1 condition A)	30g's with half-sine waveform shocks pulses of 11 milliseconds duration in each x,y,z axis. (total 18 shocks) (Test module shall be per section 8.2)	Contact Resistance: 10 mohms maximum change from initial Discontinuity: Not greater than 1 micro-second
5-2-5	Total insertion and withdrawal force (excluding latches)	Insert and withdraw a steel blade at a rate of 25±6 mm/min. Latches shall be excluded in the test. (gage dimensions refer to section 8.1)	Insertion force shall be 0.78N (2.8 oz) maximum with a maximum blade. Withdrawal force shall be 0.07N (0.25 oz) minimum with a minimum blade per contact respectively x the total contact population
5-2-6	Total insertion force (with latches)	Insert a nominal thickness PCB without the edge chamfer at a rate of 25±6 mm/min. Latches shall be included in the test.	Maximum insertion force: 15.57 kgf (34.33 lbs) - 184 ckts
5-2-7	Latch Overstress Force	Apply an actuation force on the latch at a rate of 25±6 mm/min in the fully open position and hold for 10 seconds	66.72N (15 lbs) minimum force held for 10 seconds with no damage
5-2-8	Latch Actuation Force	Apply an actuation force on the latch at a rate of 25±6 mm/min with recommended test module inserted into connector	The force to fully actuate the latch open shall be 44.48N (10 lbs) maximum per latch
5-2-9	Forklock retention force in housing	Apply an axial pullout force on the forklock in the housing at a rate of 25±6 mm/min	1.0 kgf (2.2 lbs) minimum

REVISION: A	ECR/ECN INFORMATION: EC No: S2006-0558 DATE: 2005/11/16	TITLE: 1.27mm Pitch 184 Ckts 25 Deg. DDR DIMM	SHEET No. 3 of 12
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DOCUMENT NUMBER: PS-87623-002	CREATED / REVISED BY: KY TANG 2005/11/21	CHECKED BY: JTAN 2005/11/21	APPROVED BY: GG LEE 2005/11/21
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PRODUCT SPECIFICATION

5.2 MECHANICAL PERFORMANCE (CONTINUE....)

Item		Test Condition	Requirement
5-2-10	Retention of connector to PCB	Pull or push connector with a force of 0.45kgf on connector mounted on PCB prior at a rate of 25 ± 6 mm/min	No lifting of connector from PCB when apply a force of 0.45kgf (0.99lbs)
5-2-11	Insertion Force of connector into PCB	Push connector into minimum recommended diameter holes. PCB: 1.57 ± 0.18 mm thick. Rate: 25.4 ± 6 mm/min	2.5 kgf (5.5lbs) max. per forklock
5-2-12	Module Ripout Force	Pull up from the center of the module with the latches closed at a rate of 25 ± 6 mm/min	88.96N (20 lbs) minimum retention force of module in connector with no damage.

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5.3 ENVIRONMENT PERFORMANCE

Item		Test Condition	Requirement						
5-3-1	Thermal Shock (Mil-std-202F Method 107E)	Mate connectors and expose to 5 cycles of the following:- a) -40 +0/-3 °C for 15 minutes b) +25 ± 10 for 5 minutes max. c) +65 +3/-0 for 15 minutes d) +25 ± 10 for 5 minutes max.	Contact Resistance: 10 mohms maximum change from initial Appearance: No physical damage						
5-3-2	Thermal Aging (Mil-std-202F Method 108)	Mate connectors and expose to a temperature of 85 ± 2°C for 240 ± 10 hr.	Contact Resistance: 10 mohms maximum change from initial Appearance: No physical damage						
5-3-3	Temperature Rise	Mate connectors, series four contacts and measure the temperature rise at the rated current after 4 hours	Temperature Rise: 30 °C maximum above ambient						
5-3-4	Temperature Cycling	Mate connectors and expose 335 cycles relative humidity uncontrolled with A temperature transition of 10 °C per minutes <table border="1"> <thead> <tr> <th>Temperature °C</th> <th>Duration (Min)</th> </tr> </thead> <tbody> <tr> <td>0± 3°C</td> <td>15</td> </tr> <tr> <td>+75± 3°C</td> <td>15</td> </tr> </tbody> </table> Allow to air dry for 24 hours prior to measurements	Temperature °C	Duration (Min)	0± 3°C	15	+75± 3°C	15	Contact Resistance: 10 mohms maximum change from initial Dielectric Withstanding voltage: No breakdown Insulation Resistance: 1000 Mohms minimum Appearance: No damage
Temperature °C	Duration (Min)								
0± 3°C	15								
+75± 3°C	15								

REVISION: A	ECR/ECN INFORMATION: EC No: S2006-0558 DATE: 2005/11/16	TITLE: 1.27mm Pitch 184 Ckts 25 Deg. DDR DIMM	SHEET No. 5 of 12
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5.3 ENVIRONMENT PERFORMANCE (CONTINUE....)

Item		Test Condition	Requirement
5-3-5	Humidity (Steady State)	Mate connectors and expose to a temperature of $50 \pm 2^\circ\text{C}$ with a relative humidity of $80 \pm 3\%$ for 300 hours. Remove surface moisture and air dry for 24 hours prior to measurement	Contact Resistance: 10 mohms maximum change from initial Dielectric Withstanding voltage: No breakage Insulation Resistance: 1000 Mohms minimum Appearance: No damage
5-3-6	Solderability	Steam age for 1 hours. Solder time 5 ± 0.5 seconds Solder temperature : $260 \pm 5^\circ\text{C}$. Use non-activated flux	95% of the immersed area must show no voids or pin holes
5-3-7	Resistance to Soldering Heat	Solder time: 3 ± 5 seconds Solder temperature: $260 \pm 5^\circ\text{C}$ Immerse leads to a depth of 1.57mm (.062 in) from connector body	Appearance: No blistering or deformation of plastic housing
5-3-8	IR. Process	Exposure: Molex IR. profile per section 8.4	Appearance: No blistering or deformation of plastic housing

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6.0 TEST SEQUENCE

Test Description Sequence	Test Group											
	I		II		III	IV				V		
	a	b	a	b		a	b	c	d	a	b	c
Initial Contact Resistance	1	1	1	1	1							
Durability (2 mate/unmates)	2, 8	2, 10			2, 8							
(4 mate/unmates)				2								
(5 mate/unmates)												
(24 mate/unmates)			2									
Contact Resistance	3, 5, 7, 9	3, 5, 7, 9, 11	3, 5	3, 5	3, 5, 7, 9							
Thermal Age	4											
Disturbance	6	8			6							
Thermal shock		4										
Thermal cycling		6										
Mechanical Shock			4									
Vibration				4								
Steady State Humidity					4							
Temperature Rise						1						
Solderability							1					
Resistance to soldering								1				
IR. compatibility									1			
Connector mate/unmate forces (1,2,5,25 cycles)										1		
Latch Actuation Force											1	
Module Ripout Force											2	
Connector Insertion and retention to PCB												1
Contact Retention												2
Latch Overstress Force												3
Sample size per test group	5	5	5	5	5	5	5	5	5	5	5	5

Note: Disturbance consists of a 10° rotation of the module in the connector.

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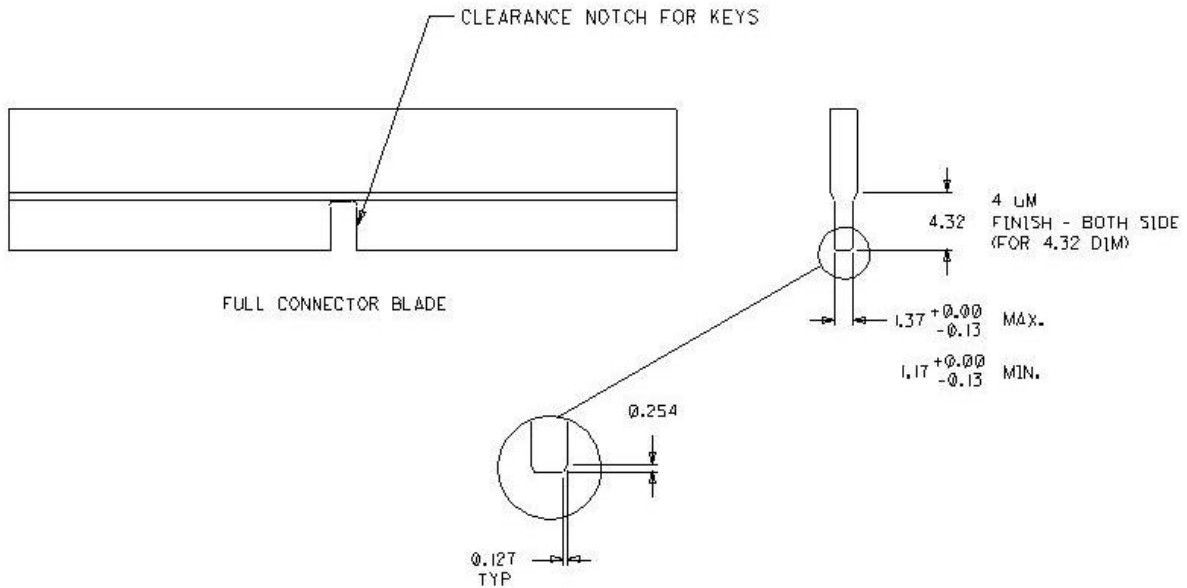
PRODUCT SPECIFICATION

7.0 PACKAGING

Part shall be packed to protect against damage during handling, transportation and storage.

8.0 GAGES, FIXTURES AND SCHEMATICS

8.1 CONTACT INSERTION AND WITHDRAWAL BLADES

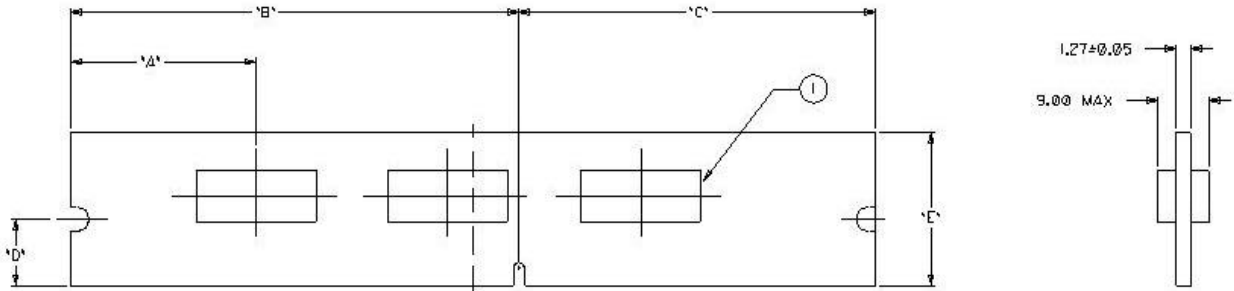


REVISION: A	ECR/ECN INFORMATION: EC No: S2006-0558 DATE: 2005/11/16	TITLE: 1.27mm Pitch 184 Ckts 25 Deg. DDR DIMM	SHEET No. 8 of 12
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8.2 SHOCK AND VIBRATION TEST MODULE



Circuit Size	JEDEC Module outline	"A" mm	"B" mm	"C" mm	"D" mm	"E" mm	SOJ Weight (gm ± 10%)	
							shock test (weighted)	Vibration test (unweighted)
184	MO-206	30.8	73.295	60.055	21.97	38.1	24.76	13.77

Notes:

1. Item 1 (weights) shall be exploited to recommended module test board. Material shall be aluminium.
2. Total weight of the finished test module shall be per the table.

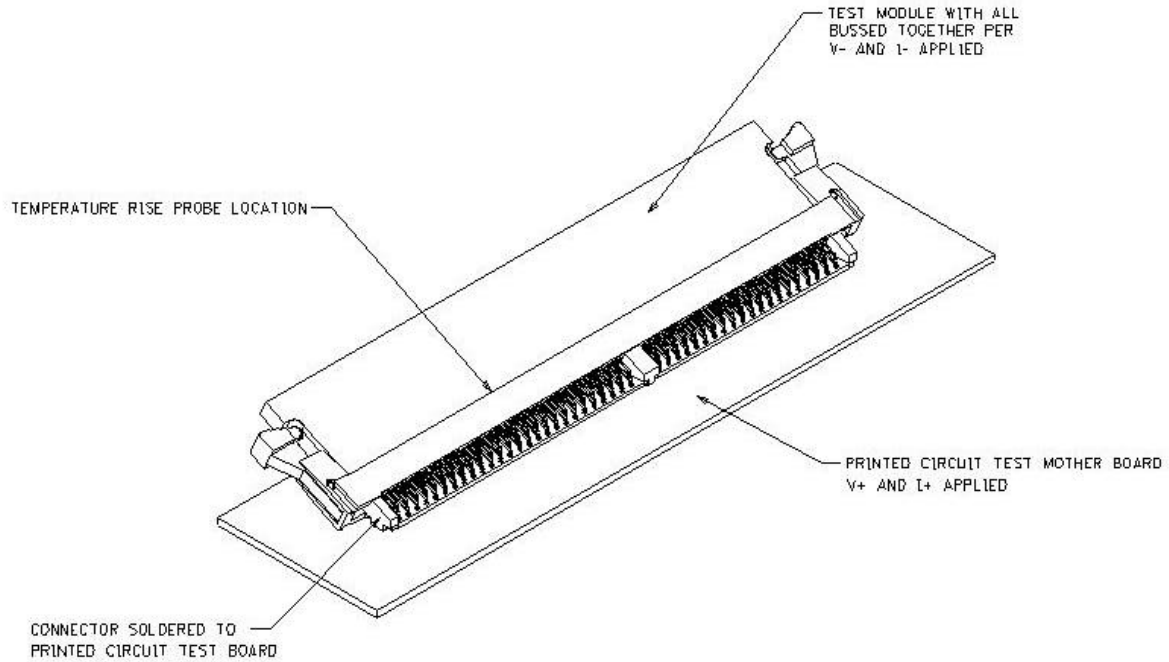
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8.3 CONTACT RESISTANCE AND TEMPERATURE RISE SETUP

Contact Resistance test arrangement and Temp / Rise measurement location

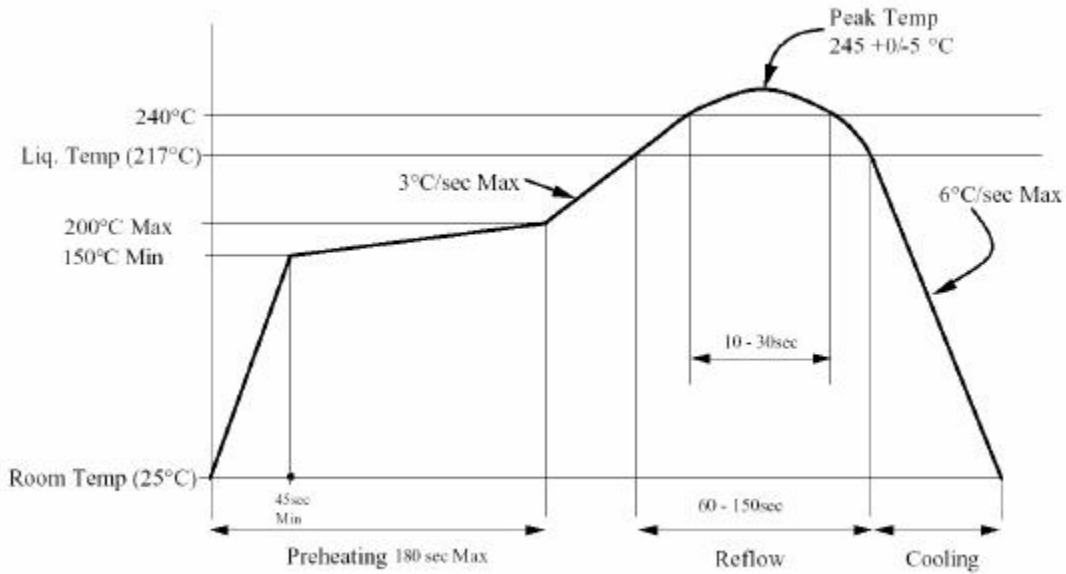


REVISION: A	ECR/ECN INFORMATION: EC No: S2006-0558 DATE: 2005/11/16	TITLE: 1.27mm Pitch 184 Ckts 25 Deg. DDR DIMM	SHEET No. 10 of 12
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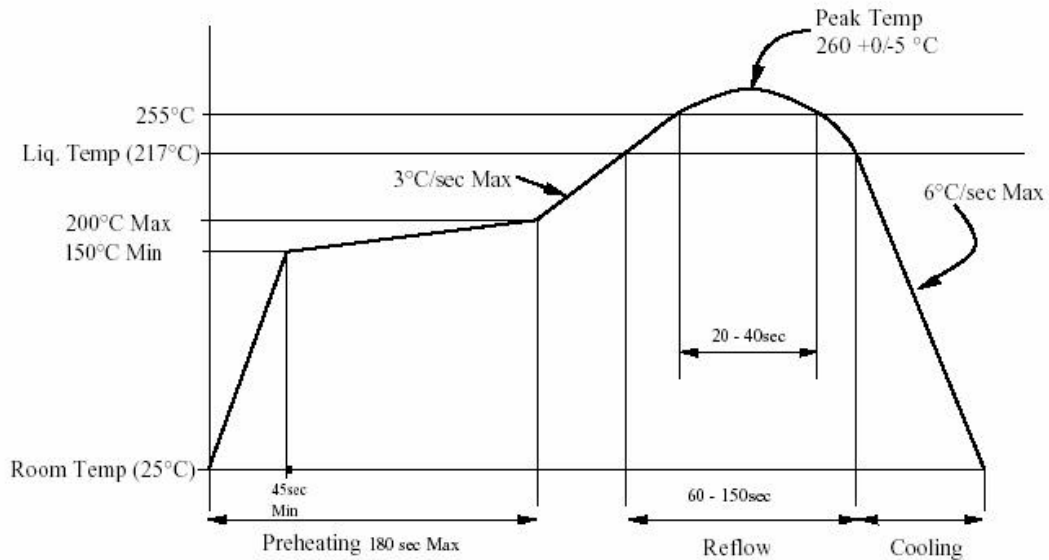


PRODUCT SPECIFICATION

8.4 RECOMMENDED PB-FREE REFLOW PROFILES



LEAD-FREE PROFILE FOR PEAK REFLOW - 245°C



LEAD-FREE PROFILE FOR PEAK REFLOW - 260°C

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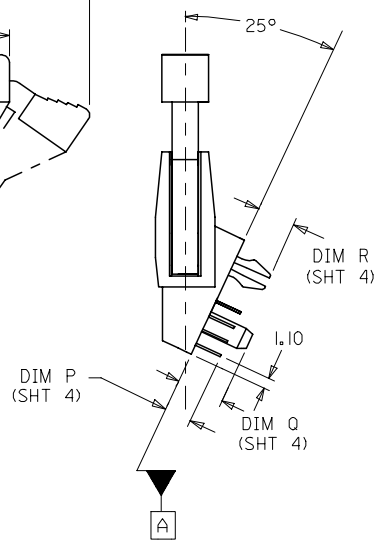
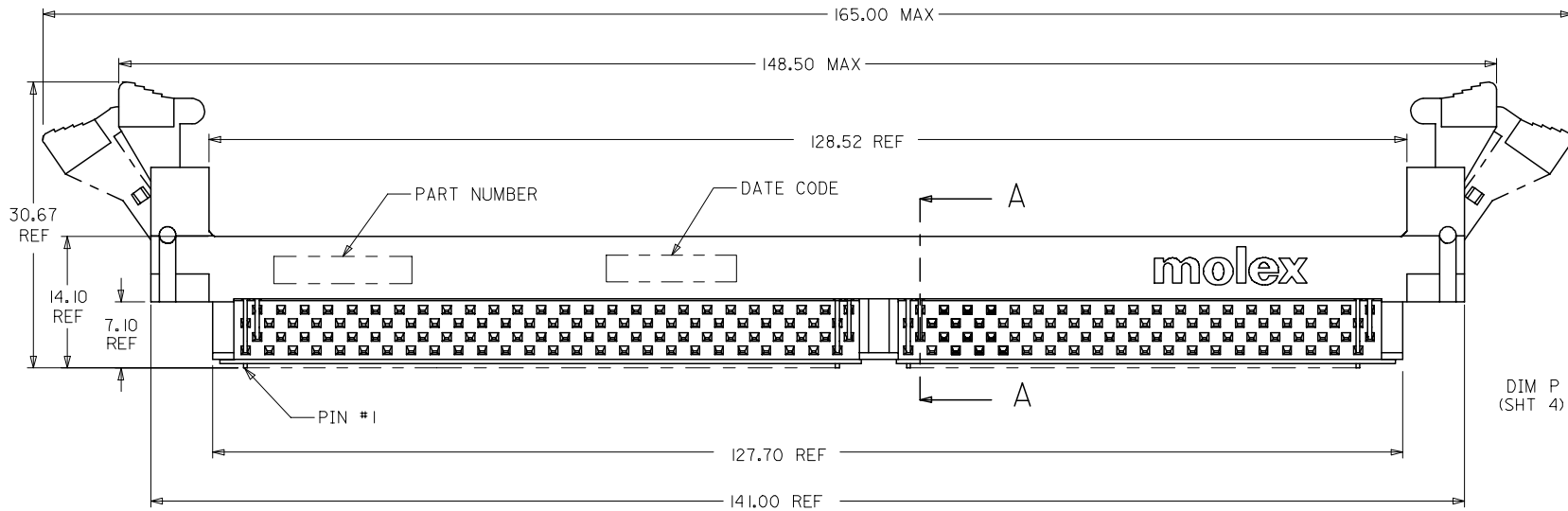
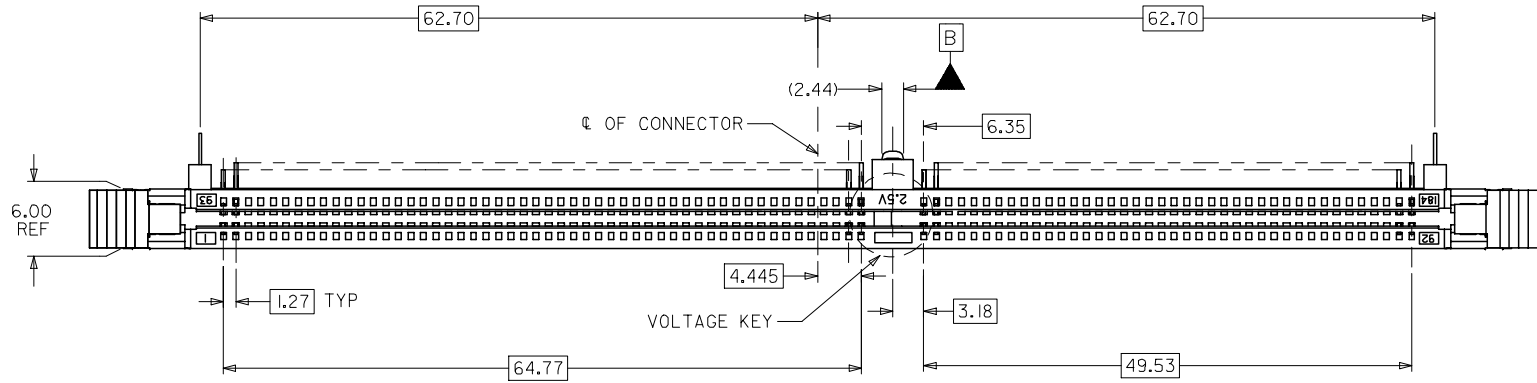
PRODUCT SPECIFICATION

Notes :

- 1) Temperature indicated refers to the PCB surface temperature at soldertail area.
- 2) Connector can withstand up to 2 reflow cycles with a cool-down to room temperature in-between.
- 3) Actual reflow profile also depends on equipment, solder paste, PCB thickness, and other components on the board. Please consult your solder paste & reflow equipment manufacturer for their recommendations to adopt a suitable process.

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10 9 8 7 6 5 4 3 2 1



- NOTES:
- MATERIALS: HOUSING & BASEPLATE - LCP, GLASS FILLED, UL 94V-0, COLOR: BLACK
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0, COLOR: BEIGE
TERMINAL AND FORKLOCK - COPPER ALLOY
 - FINISHES: CONTACT AREA: SEE TABLE ON SHEET 4
SOLDER TAILS: 2.54µm/100µ" MIN. TIN
OVER 1.27mm/50µ" MIN. NICKEL
 - PRODUCT SPECIFICATIONS: PS-87623-002 FOR PERFORMANCE SPECIFICATIONS.
 - DATE CODE SHALL BE MARKED LEGIBLY AS SHOWN: XX XX
YEAR — WEEK
 - PART NUMBER SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX
REFER TO TABLE

OBS TIN/LEAD P/N	EC NO: S2006-0734	2006/02/27	QUALITY SYMBOLS
	DRWN:MLONG	2006/02/28	
	CHKD:HO	2006/03/01	
	APPR:GJLEE		
REV	DESCRIPTION		

QUALITY SYMBOLS	▽=0	
	∇=0	
GENERAL TOLERANCES (UNLESS SPECIFIED)		
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

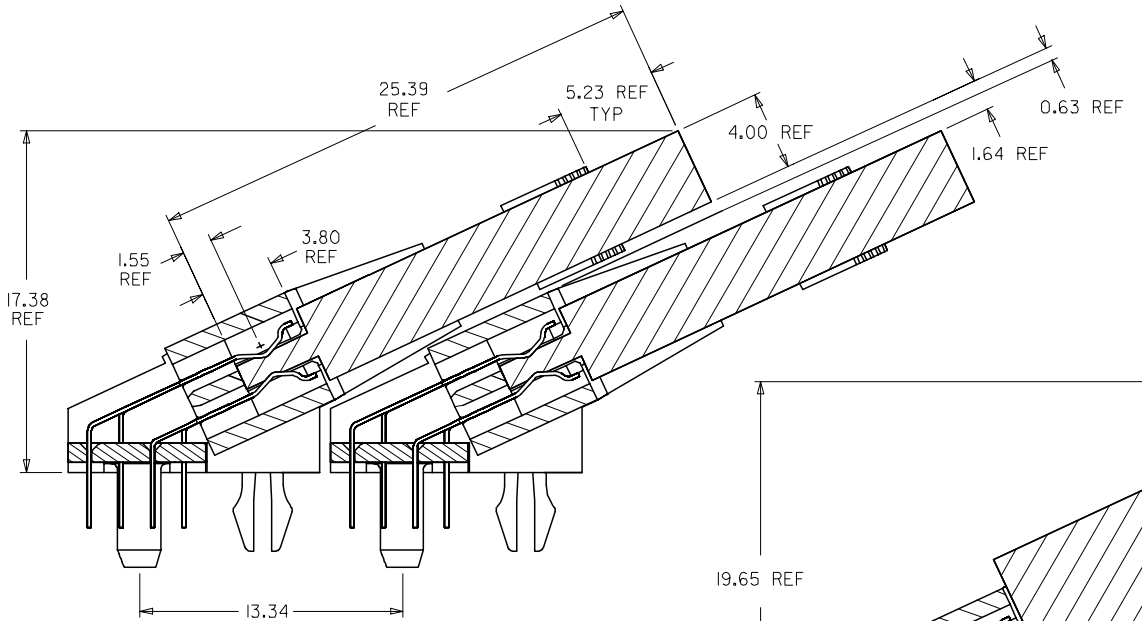
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MM ONLY	
DRAWN BY	DATE
LPL IM	2000/01/10
CHECKED BY	DATE
DSOH	2000/02/02
APPROVED BY	DATE
SKTOH	2000/02/02
MATERIAL NO.	
SEE TABLE	
SIZE	A3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	
TITLE		
DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.		
MOLEX MOLEX INCORPORATED		
MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE TABLE	SD-87623-001	1 OF 4

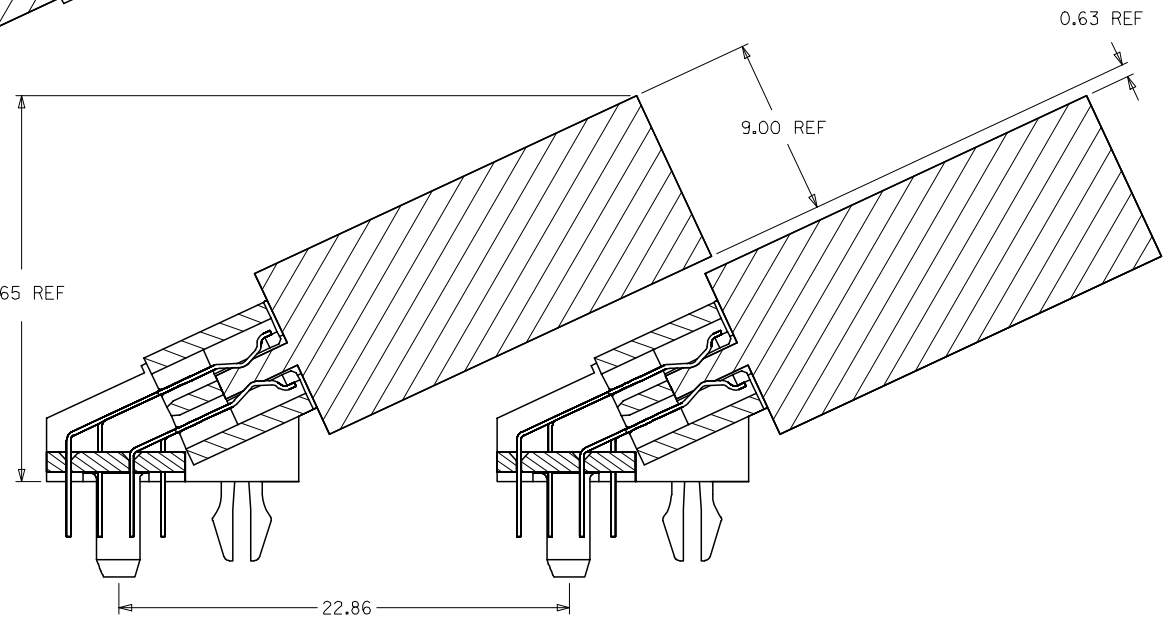
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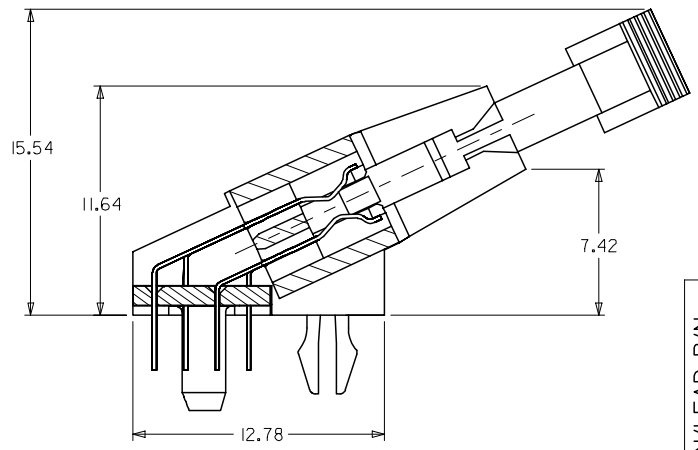
F
E
D
C
B
A



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00 mm THICK
MODULE (TYPICAL TSOP PACKAGING)



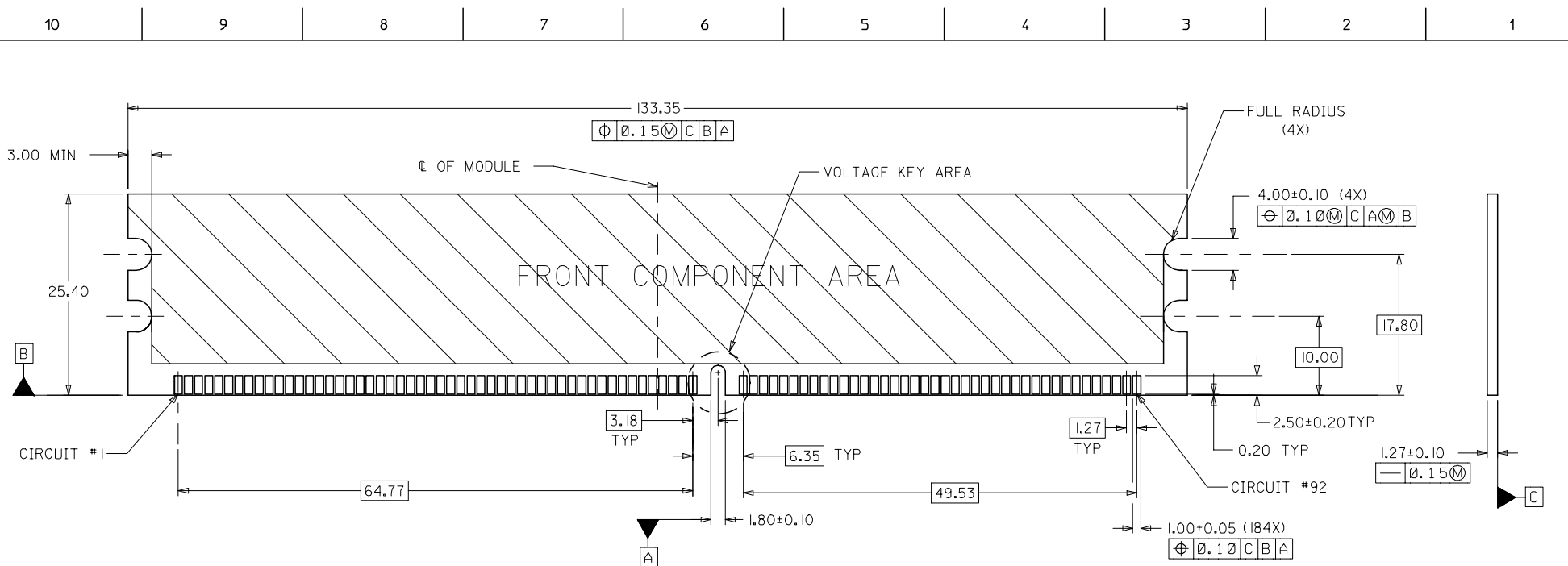
MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 9.00 mm THICK
MODULE (TYPICAL SOJ PACKAGING)



SECTION A-A

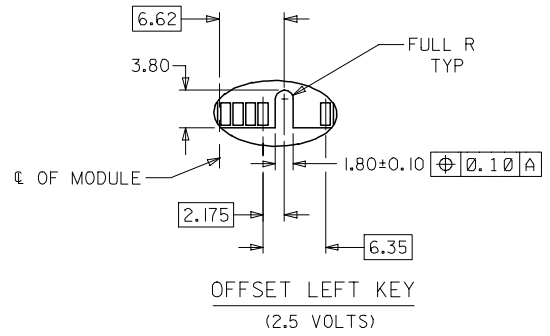
OBS TIN/LEAD P/N EC NO: S2006-0734 DRWN:MLONG CHKD:IHO APPR:GJLEE	2006/02/27	2006/02/28	2006/03/01	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.25</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td colspan="3">ANGULAR ± 5 °</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.25	± ---	1 PLACE	± ---	± ---	ANGULAR ± 5 °			DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																								
	4 PLACES	± ---	± ---																								
	3 PLACES	± ---	± ---																								
2 PLACES	± 0.25	± ---																									
1 PLACE	± ---	± ---																									
ANGULAR ± 5 °																											
DESCRIPTION	DRAWN BY	DATE	TITLE	DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.																							
REV	CHECKED BY	DATE	APPROVED BY	DATE	MOLEX INCORPORATED																						
	APPROVED BY	DATE	SKTOH	2000/02/02	DOCUMENT NO. SD-87623-001																						
	MATERIAL NO.			SEE TABLE			SHEET NO. 2 OF 4																				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					SIZE A3			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																			

9 8 7 6 5 4 3 2 1



RECOMMENDED MODULE LAYOUT
 (PER JEDEC STANDARD MO-206, 184 CKT.)
 UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE = ±0.13

VOLTAGE KEY AREA



OBS	TIN/LEAD P/N
EC NO:	S2006-0734
DRWN:	M:LONG 2006/02/27
CHKD:	I:HO 2006/02/28
APPR:	G:GLEE 2006/03/01
REV	DESCRIPTION

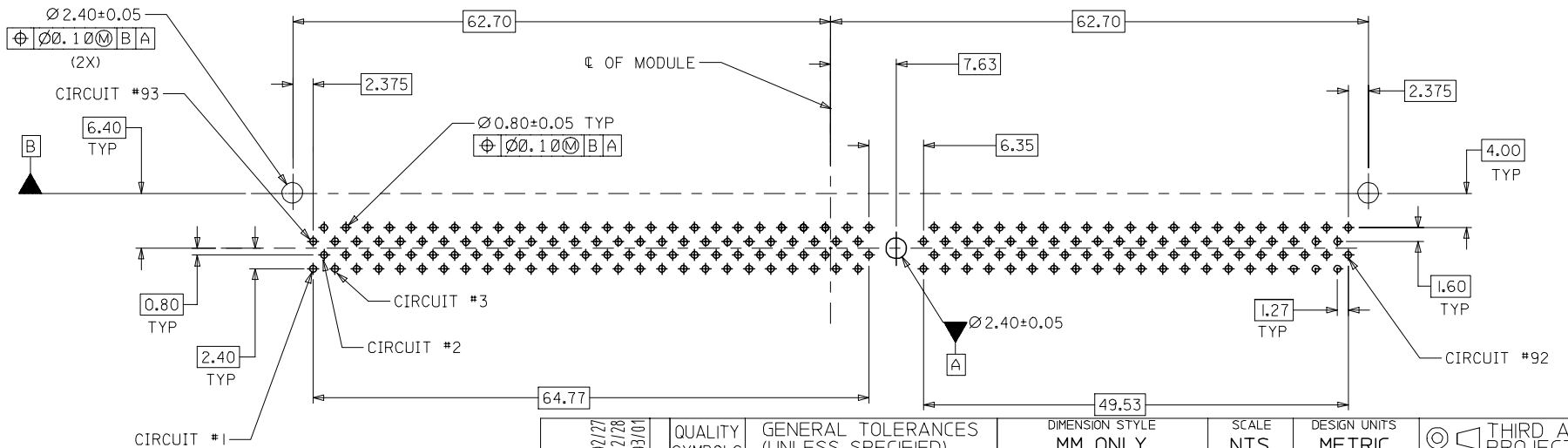
QUALITY SYMBOLS	▽=0
▽=0	▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		NTS	METRIC	
DRAWN BY	DATE	TITLE	DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.	
LPL IM	2000/01/10			
CHECKED BY	DATE			
DSOH	2000/02/02			
APPROVED BY	DATE			
SKT0H	2000/02/02			
MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
SEE TABLE	SD-87623-001	3 OF 4		

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PART NUMBER	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH 0±0.25	FORK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA
87623-2001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
87623-2011			3.18	4.83	3.94		
87623-2012			3.18	3.18	3.18		
87623-2013			3.81	4.83	4.42	2.84	
87623-2101			2.79	3.18	3.18	1.57	
87623-2111			3.18	4.83	3.94		
87623-2113			3.81	4.83	4.42		
87623-2115			3.18	3.18	3.18	1.57	SELECTIVE GOLD 0.76µM/30µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL



RECOMMENDED
P.C. BOARD HOLE PATTERN
(CONNECTOR SIDE)

OBS TIN/LEAD P/N
EC NO: S2006-0734
DRWN:HLONG
CHKD:HO
APPR:GJLEE

QUALITY SYMBOLS
▽=0
△=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
LPL IM	2000/01/10
CHECKED BY	DATE
DSOH	2000/02/02
APPROVED BY	DATE
SKTOH	2000/02/02

MATERIAL NO. SEE TABLE

SCALE NTS
DESIGN UNITS METRIC
THIRD ANGLE PROJECTION

TITLE
DDR DIMM, 1.27MM PITCH
184 CKTS, 25 DEG.

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DOCUMENT NO. SD-87623-001
SHEET NO. 4 OF 4

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